



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Confirmation No. 4508
Toshifumi KIMBA et al. : Docket No. 2000-1706A
Serial No. 09/734,737 : Group Art Unit 2877
Filed December 13, 2000 : Examiner Hoa Q. Pham

SUBSTRATE FILM THICKNESS
MEASUREMENT METHOD,
SUBSTRATE FILM THICKNESS
MEASUREMENT APPARATUS
AND SUBSTRATE PROCESSING
APPARATUS

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Responsive to the Office Action of February 26, 2003, please amend the above-identified application as follows.

In the Specification and Abstract:

Kindly replace the original specification and abstract with the enclosed substitute specification and abstract.

In the Claims:

Kindly cancel claims 1-19 presently pending in the application without prejudice.

RECEIVED
MAY 30 2003
TECHNOLOGICAL CENTER 2800